



MAK-141

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

By: \_\_\_\_\_

Date: Feb 26, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Robert-Christian Hagen et al.  
Applic. No. : 09/993,266  
Filed : November 19, 2001  
Title : Electronic Component with Shielding and  
Method for its Production

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,  
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified application as follows:

In the Claims:

Claim 13 (amended). A method for producing electronic components with shielding, which comprises the steps of:

providing a semiconductor wafer functioning as a semiconductor substrate formed of a semiconductor material and having an